

EAST Search History

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|--|---|------------------|---------|------------------|
| L1 | 3 | ("6333563" or "20040173914" or "6806560" or "66327040").pn. | US-PGPU B; USPAT | OR | ON | 2007/03/25 10:41 |
| L15 | 109 | (underfill\$3 near5 ("CTE" and (thermal near2 expansion))) | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/03/25 11:08 |
| L16 | 95 | 15 and (patial or partially or size or micron or diameter) | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/03/25 11:09 |
| L20 | 5 | ((underfill\$3 near2 microns)and (filler with particle with(size or diameter or radius or radii))) | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/03/25 11:40 |
| L21 | 17 | ("5001542" "5907190" "5981313" "5982631" "6049038" "6121689" "6133639" "6137183").PN. OR ("6373142").URPN. | US-PGPU B; USPAT; USOCR | OR | ON | 2007/03/25 11:45 |

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| L28 | 50 | ((underfill\$3 or encapsulant or encapsulat\$3) with(filler or particale or metal or oxide) with ("32" or "30" or "300") with micron)) | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2007/03/25 11:56 |
| L29 | 180 | (underfill\$3 with(filler or particle or metal or oxide) with (size or diameter or radius or micron)) | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2007/03/25 12:46 |
| L30 | 17 | ("5001542" "5907190" "5981313" "5982631" "6049038" "6121689" "6133639" "6137183"). PN. OR ("6373142"). URPN. | US-PGPU B; USPAT; USOCR | OR | ON | 2007/03/25 12:38 |
| L31 | 106 | ((underfill\$3 or encapsulant or encapsulat\$3)near50 (gap or space) with(filler near100 (size or diameter or radius or radii))) | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2007/03/25 13:20 |
| L35 | 33 | ("5953814" "5968670" "5060844" "5784261" "6333563" "6632704" "6674172" "6806560" "6015722" "6048656" "6177728" "6294271" "6310120" "6333563" "6506869" "6572980" "6586846"). PN. | US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2007/03/25 13:38 |

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| L36 | 6 | 35 and (filler and gap and (solder\$3 and ball and size)) | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2007/03/25 13:44 |
| L42 | 8 | ((underfill\$3 or encapsulat\$3 or encapsulant) with filler)and gap and (solder\$3 same ball same size)same (join\$3 or bond\$3) same (substrate near5 (circuit near2 board))) | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2007/03/25 14:31 |
| L44 | 4 | ((underfill\$3 or encapsulat\$3 or encapsulant) with filler)and ((gap near100 height) with (("300" or "900") near50 microns)) | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2007/03/25 14:04 |
| L45 | 41 | ("5088189" "5128746" "5136365" "5349240" "5376403" "5587342" "5629566" "5710071" "5729440" "5742100" "5751068" "5770476" "5801072" "5801449" "5861323" "5985043" "5985456" "6077380"). PN. OR ("6335571"). URPN. | US-PGPU B; USPAT; USOCR | OR | ON | 2007/03/25 14:08 |
| L47 | 298 | 228/215.ccls. | US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2007/03/25 14:32 |

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| L48 | 488 | 228/178.ccls. | US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2007/03/25 14:32 |
| L49 | 1091 | 228/180.1.ccls. | US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2007/03/25 14:32 |
| L50 | 991 | 228/180.21.ccls. | US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2007/03/25 14:32 |
| L51 | 1297 | 228/180.22.ccls. | US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2007/03/25 14:32 |
| L52 | 119 | 228/244.ccls. | US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2007/03/25 14:32 |

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| L53 | 3924 | L47 or L48 or L49 or L50 or L51 or L52 | US-PGPU B; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/03/25 14:32 |
| L56 | 3 | L53 and (((underfill\$3 or encapsulat\$3 or encapsulant) and filler)and gap and (solder\$3 same ball same size)and (join\$3 or bond\$3) and (substrate same (circuit with board))) | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/03/25 14:34 |